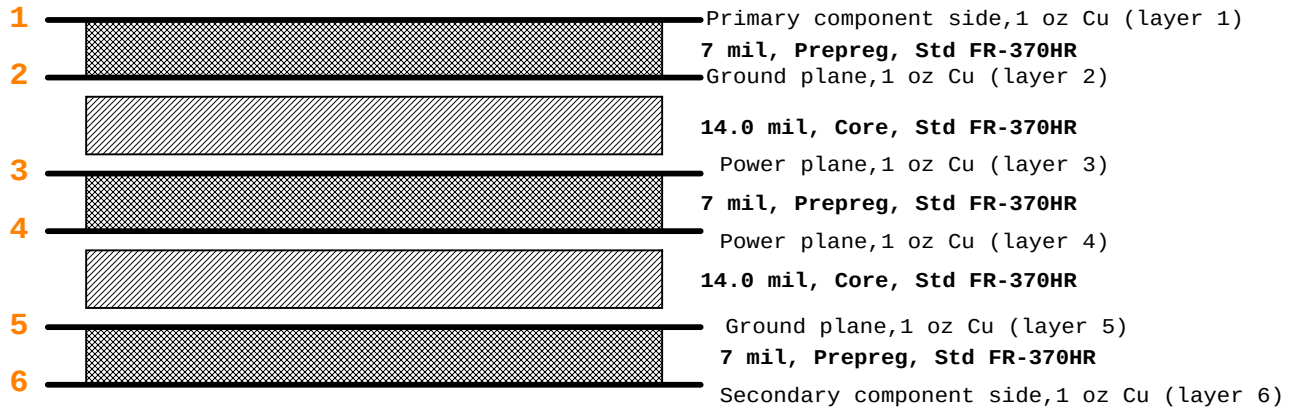
LAYOUT NOTES:
1) 6 layer board.
2) Use standard FR-370HR.
3) 5% impedance tolerance.
4) Minimum 4 standoffs on each corner of board. (0.156 X 4).

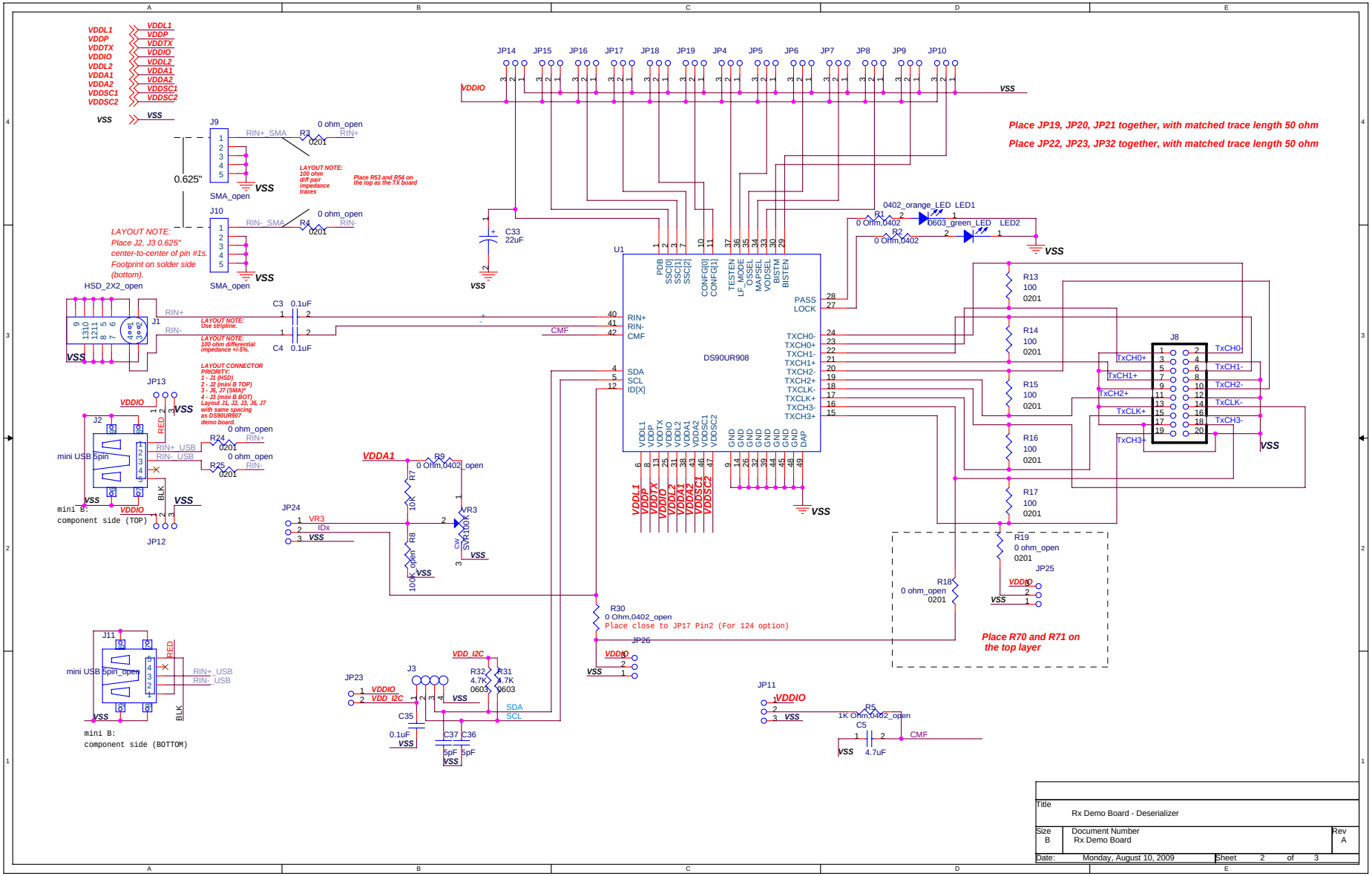


FPD LINK II/III - FPD LINK

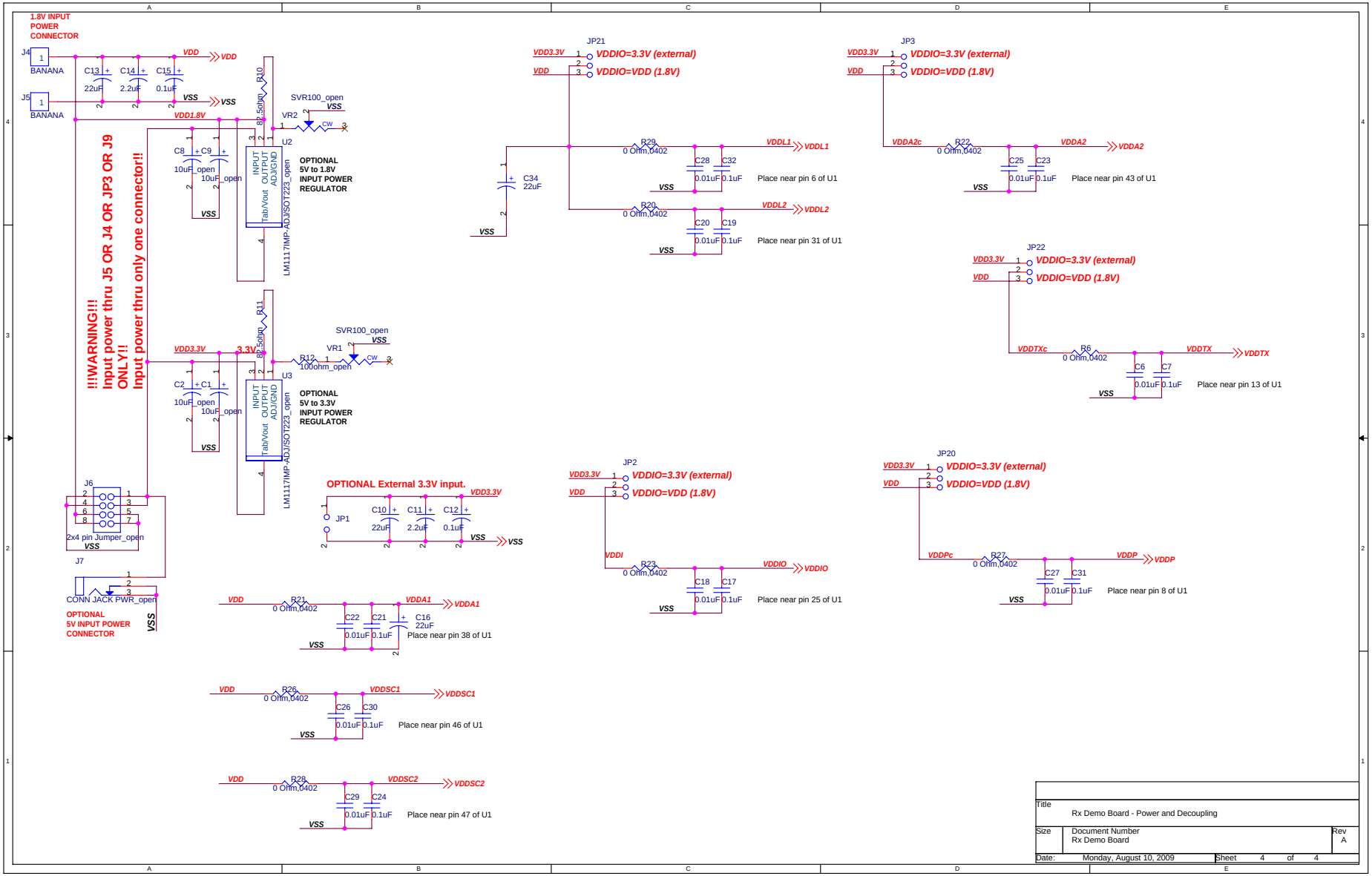
Core Material

Prepreg Material

Title: Rx Demo Board - Board Stackup		
Size: A	Document Number: Rx Demo Board	Rev: B
Date: Monday, August 10, 2009	Sheet 1 of 3	



Title	Rx Demo Board - Deserializer	
Size B	Document Number Rx Demo Board	Rev A
Date: Monday, August 10, 2009	Sheet 2 of 3	


1.8V INPUT POWER CONNECTOR
J4
BANANA
J5
BANANA
VDD
VSS
VDD1.8V
C13 22uF
C14 2.2uF
C15 0.1uF
R10 82.5ohm
SVR100_open
VR2
U2
C8 10uF_open
C9 10uF_open
INPUT
OUTPUT
ADJ/GND
Tab/Vout
LM1117IMP-ADJ/SOT223_open
OPTIONAL 5V to 1.8V INPUT POWER REGULATOR
!!!WARNING!!!
Input power thru J5 OR J4 OR JP3 OR J9 ONLY!!
Input power thru only one connector!!
VDD3.3V
3.3V
R11 82.5ohm
R12 100ohm_open
VR1
U3
C2 10uF_open
C1 10uF_open
OPTIONAL 5V to 3.3V INPUT POWER REGULATOR
J6
2x4 pin Jumper_open
J7
CONN JACK PWR_open
OPTIONAL 5V INPUT POWER CONNECTOR
OPTIONAL External 3.3V input.
JP1
C10 22uF
C11 2.2uF
C12 0.1uF
JP21
VDDIO=3.3V (external)
VDDIO=VDD (1.8V)
R29 0 Ohm,0402
R30 0 Ohm,0402
C34 22uF
C28 0.01uF
C32 0.1uF
C20 0.01uF
C19 0.1uF
VDDL1
VDDL2
Place near pin 6 of U1
Place near pin 31 of U1
JP3
VDDA2c
R22 0 Ohm,0402
VDDA2
C25 0.01uF
C23 0.1uF
Place near pin 43 of U1
JP22
VDDTXc
R6 0 Ohm,0402
VDDTX
C6 0.01uF
C7 0.1uF
Place near pin 13 of U1
JP2
VDDI
R23 0 Ohm,0402
VDDIO
C18 0.01uF
C17 0.1uF
Place near pin 25 of U1
JP20
VDDPc
R27 0 Ohm,0402
VDDP
C27 0.01uF
C31 0.1uF
Place near pin 8 of U1
R21 0 Ohm,0402
VDDA1
C22 0.01uF
C21 0.1uF
C16 22uF
Place near pin 38 of U1
R26 0 Ohm,0402
VDDSC1
C26 0.01uF
C30 0.1uF
Place near pin 46 of U1
R28 0 Ohm,0402
VDDSC2
C29 0.01uF
C24 0.1uF
Place near pin 47 of U1
Title
Rx Demo Board - Power and Decoupling
Size
Document Number
Rx Demo Board
Rev
A
Date: Monday, August 10, 2009
Sheet 4 of 4

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